

ABSTRACT OF DISCLOSURE

An object of the invention is to provide a sputtering device which can be increased distribution of film formation and coverage distribution
5 better than prior sputtering devices. Thus, this invention is that, in the sputtering device constituted of at least a substrate, a substrate holder for holding the substrate, at least one target for forming a thin film on the substrate, at least one sputtering cathodes each of which has the target and magnets arranged behind the substrate, an axis of the target is inclined to
10 an axis of the sputtering cathode, and the sputtering cathode is rotated in its axis to make the target swing to the substrate.